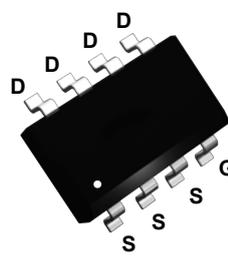
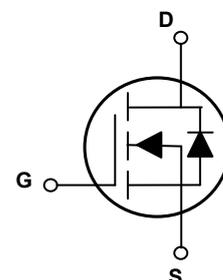


## Main Product Characteristics

$V_{(BR)DSS}$	30V
$R_{DS(ON)}$	3.5m $\Omega$ (Max.)
$I_D$	22A



SOP-8



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFQ0390 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, @ Steady-State ( $T_A=25^\circ\text{C}$ ) <sup>1</sup>	$I_D$	22	A
Continuous Drain Current, @ Steady-State ( $T_A=70^\circ\text{C}$ ) <sup>1</sup>		17	A
Pulsed Drain Current ( $T_A=25^\circ\text{C}$ ) <sup>2</sup>	$I_{DM}$	88	A
Power Dissipation ( $T_A=25^\circ\text{C}$ ) <sup>3</sup>	$P_D$	2.6	W
Single Pulse Avalanche Energy	$E_{AS}$	289	mJ
Single Pulse Current	$I_{AS}$	34	A
Thermal Resistance, Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +150	$^\circ\text{C}$
Soldering Temperature (SMD)	$T_{sold}$	260	$^\circ\text{C}$

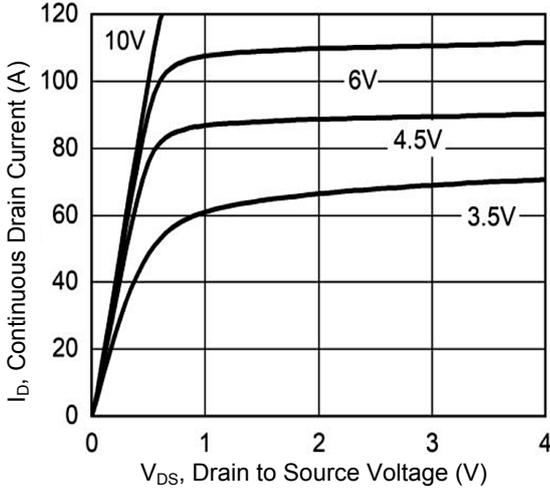
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	1.0	$\mu A$
		$V_{DS}=30V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	1.5	-	
Static Drain-to-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	2.6	3.5	m $\Omega$
		$V_{GS}=4.5V, I_D=15A$	-	4.2	5.6	
Gate-to-Source Forward Leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.1	-	2.5	V
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{ISS}$	$V_{GS}=0V, V_{DS}=15V, f=1\text{MHz}$	-	3260	-	pF
Output Capacitance	$C_{OSS}$		-	344	-	
Reverse Transfer Capacitance	$C_{RSS}$		-	302	-	
Total Gate Charge <sup>4,5</sup>	$Q_g$	$I_D=20A, V_{DD}=15V, V_{GS}=10V$	-	56	-	nC
Gate-to-Source Charge <sup>4,5</sup>	$Q_{gs}$		-	7.5	-	
Gate-to-Drain ("Miller") Charge <sup>4,5</sup>	$Q_{gd}$		-	15	-	
Turn-On Delay Time <sup>4,5</sup>	$t_{d(on)}$	$V_{DD}=15V, V_{GS}=10V, R_G=3\Omega, I_D=20A$	-	25	-	nS
Rise Time <sup>4,5</sup>	$t_r$		-	21	-	
Turn-Off Delay Time <sup>4,5</sup>	$t_{d(off)}$		-	49	-	
Fall Time <sup>4,5</sup>	$t_f$		-	27	-	
Gate Resistance	$R_g$	$f=1\text{MHz}$	-	1.8	-	$\Omega$
<b>Drain-Source Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	22	A
Diode Pulse Current	$I_{S,pulse}$		-	-	88	A
Diode Forward Voltage	$V_{SD}$	$I_S=10A, V_{GS}=0V$	-	-	1.4	V
Reverse Recovery Time <sup>4</sup>	$t_{rr}$	$I_S=20A, V_{GS}=0V, V_R=20V, di_F/dt=100A/\mu s$	-	56	-	nS
Reverse Recovery Charge <sup>4</sup>	$Q_{rr}$		-	42	-	nC

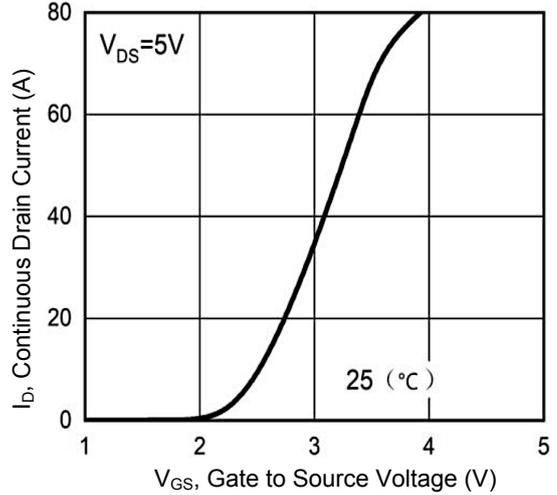
Notes:

1. The rated value only refers to the maximum absolute value under the case temperature of  $25^\circ\text{C}$  in the manual. If the case temperature is higher than  $25^\circ\text{C}$ , the frequency needs to be reduced according to the actual environmental conditions.
2. Pulse time of  $5\mu s$ , pulse width limited by maximum junction temperature.
3. The dissipated power value will change with the temperature. When it is greater than  $25^\circ\text{C}$ , the dissipated power value will decrease by  $0.74^\circ\text{C/W}$  for every 1 degree of temperature increase.
4. Pulse test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
5. Basically unaffected by operating temperature.

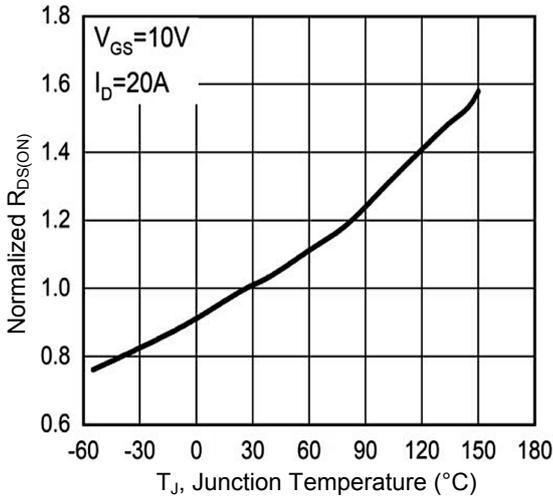
**Typical Electrical and Thermal Characteristic Curves**



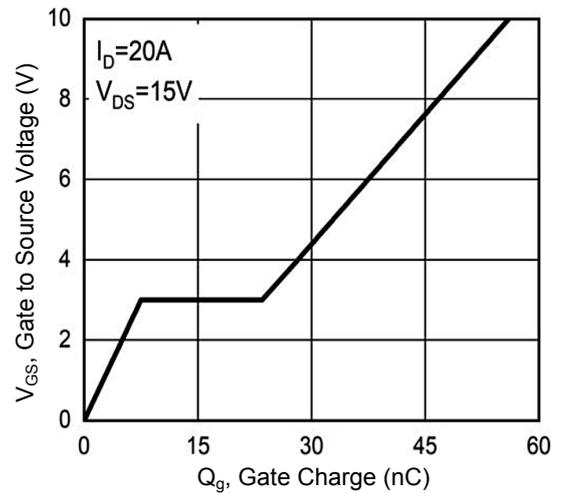
**Figure 1. Output Characteristics**



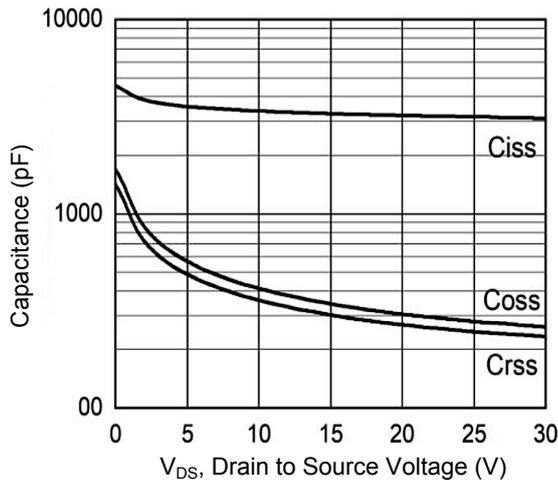
**Figure 2. Transfer Characteristics**



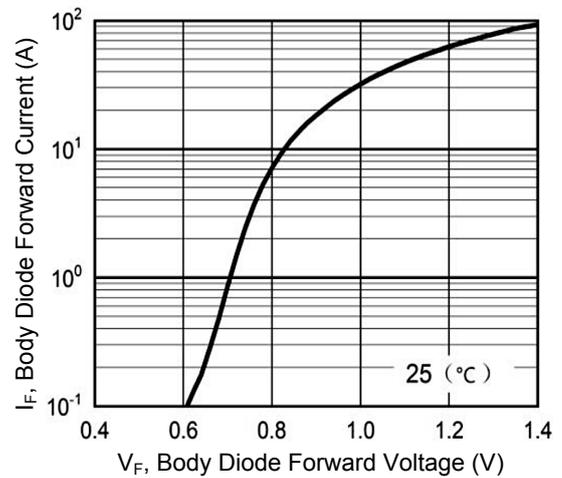
**Figure 3. Normalized  $R_{DS(ON)}$  vs.  $T_J$**



**Figure 4. Gate Charge Characteristics**

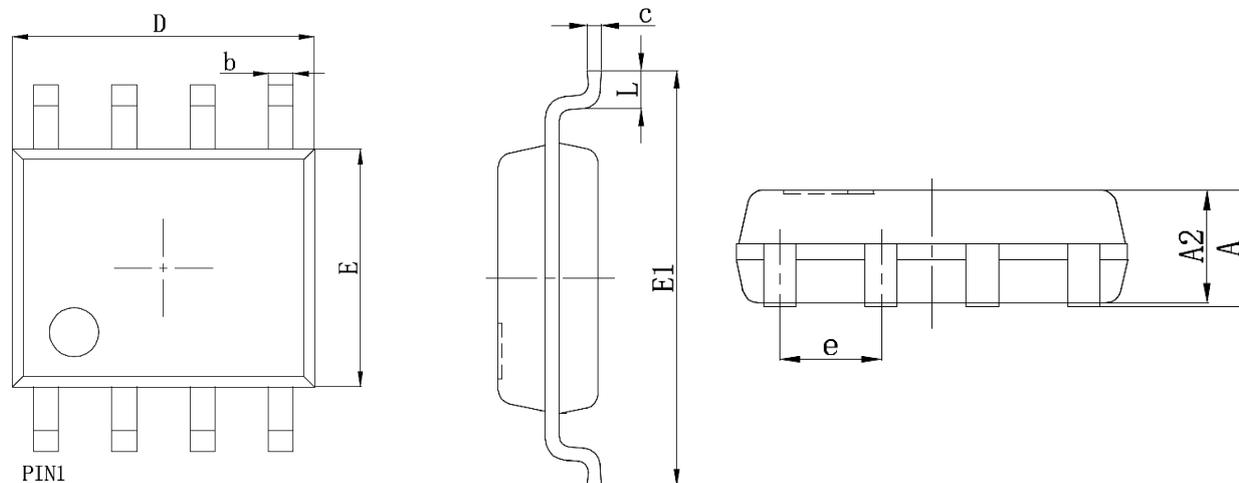


**Figure 5. Capacitance Characteristics**



**Figure 6. Body Diode Characteristics**

**Package Outline Dimensions (SOP-8)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.30	1.70	0.051	0.067
A2	1.25	1.55	0.049	0.061
c	0.17	0.25	0.007	0.010
E	3.80	4.00	0.150	0.157
E1	5.80	6.20	0.228	0.244
L	0.45	0.75	0.018	0.030
b	0.33	0.51	0.013	0.020
D	4.80	5.00	0.189	0.197
e	1.27 BSC		0.050 BSC	

**Order information**

Device	Package	Marking	Packaging	SPQ
GSFQ0390	SOP-8	Q0390	Tape & Reel	3,000 Pcs / Reel